

Next-generation ultra-high-speed microwave Photonic integrATed circuiTs using advancEd hybRid iNtegration

The PATTERN project will develop the world's first Process and Assembly Design Kits (PDK & ADK) for microwave photonics at ultra-high frequencies (100+ GHz) as well as new methods of heterogeneous integration of III-V gain materials (e.g. InP) and BiCMOS drivers with electro-optic and nonlinear platforms such as lithium niobate on insulator (LNOI). The project envisions to:

DESIGN

novel advanced PIC building blocks such as **acousto-optic modulators** (AOMs) by combining surface acoustic waveguides (SAWs) and waveguides as well as **magneto-optic isolators** through hybrid integration of yttrium iron garnet (YIG) and LNOI



ENABLE

unrivalled new PIC functionalities, components and subsystems such as **fast tuneable lasers** for a vast range of applications, from quantum computing and quantum communication to ultra-high-speed telecom, optical computing, sensing and metrology

a wafer-scale solution for heterogeneous integration of indium phosphite (InP) gain chips and photodetectors on top of an LNOI platform by means such as flip-chip bonding and micro-transfer print

DEVELOP



all processing steps and expertise for microwave photonics at ultra-high speeds (above 100 GHz), from PDK components such as LNOI modulators and InP detectors to assembly and packaging as well as BiCMOS drivers and design software for microwave photonics

DEMONSTRATE

the capabilities of the new ultra-high-speed components and heterogeneous integration through **six major prototypes** for different end-user applications in the fields of **quantum computing** and **sensing** to **space communication systems** and **low-noise microwave generation (OEOs and OPLLs)**



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